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DATE:	October 21, 2002
CLIENT NO.:	M4065.0184/P184
MESSAGE TO:	Examiner Chuong Luu
COMPANY:	U.S. Patent and Trademark Office, Art Unit 2825
FAX NUMBER:	703-872-9318
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PAGES (Including Cover Sheet): 4 **HARD COPY TO FOLLOW:** ☐ YES ☒ NO

Please file the attached Request for Reconsideration in U.S. Patent Application No. 09/594,510. The undersigned certifies that the attached Request for Reconsideration is being transmitted to the U.S. Patent and Trademark Office by facsimile transmission on October 21, 2002.

Mark J. Thronson, Reg. No. 33,082

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Response #10 Filed 10/23/02

Docket No.: M4065.0184/P184
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Alan G. Wood, et al.

Application No.: 09/594,510

Group Art Unit: 2825

Filed: June 16, 2000

Examiner: C. Luu

For: SEMICONDUCTOR DEVICE PACKAGE AND METHOD

REQUEST FOR RECONSIDERATION

Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated July 19, 2002 (Paper No. 9), please reconsider the above-identified U.S. Patent application in light of the following remarks:

Claims 1, 5-6, 8, 10-12 and 19 are rejected under 35 U.S.C. § 102 as being anticipated by Kata. Applicants respectfully traverse the rejection and request reconsideration. Claim 1 recites a "method of making semiconductor device packages." The method includes the steps of "testing semiconductor devices in [a] wafer" and, "subsequently, dicing [a] layered assembly." Kata fails to disclose or suggest the step of "testing semiconductor devices in said wafer." The step of "testing semiconductor devices in said wafer," before the dicing of the layered assembly, is an important aspect of the claimed invention. Please refer to Applicants' specification, page 2, lines 18+. Claims 2-10 depend from independent claim 1 and are believed to be allowable along with claim 1 and for other reasons.

Claim 11 (as amended) recites "forming a layered assembly by attaching a semiconductor device and a stiff metal layer to a dielectric layer." Kata fails to disclose or suggest a "stiff metal layer" attached to a semiconductor wafer but discloses a plurality of electrode pads on one side of the semiconductor devices. In contrast to the claimed invention, the electrode pads disclosed in Kata are not a metal layer formed between the semiconductor device and the dielectric layer. The "stiff metal layer" is an important aspect of the invention of claim 11. Claims 12-18 depend from independent claim 11 and are believed to be allowable along with claim 11 and for other reasons.

Claim 19 recites "aligning a semiconductor wafer with respect to a dielectric tape." Kata does not disclose or suggest the alignment of the semiconductor wafer with respect to a dielectric tape. Furthermore, claim 19 also recites a method of making a semiconductor device package whereby the semiconductor device in the wafer is connected to ball grid arrays on the dielectric tape. Kata fails to disclose or suggest ball grid arrays on a dielectric tape but discloses a metal bump which is formed by plating. (col. 7, lines 39-42). Claims 20-23 depend from independent claim 19 and are believed to be allowable along with claim 19 and for other reasons.

Claims 35 and 37 are rejected under 35 U.S.C. § 103 as being unpatentable over Kata in view of Farnworth, and further view of Kobayashi. Applicants respectfully traverse the rejection and request reconsideration. Claim 35 recites "testing said semiconductor devices through several ball grid arrays." Kata fails to disclose or suggest the step of "testing ... semiconductor devices through ... ball grid arrays." Furthermore, Farnworth fails to disclose or suggest using the ball grid arrays to test the semiconductor, but rather, Farnworth discloses using a ball grid array for attachment to a circuit board, for connecting each lead to an electrical apparatus. Testing the semiconductor devices through the ball grid arrays is an important aspect of the invention of claim 35. Claims 36-38 depends from independent claim 35 and is believed to be allowable along with claim 35 and for other reasons.

Application No.: 09/594,510 Docket No.: M4065.0184/P184

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to withdraw the outstanding rejection of the claims and to pass this application to issue.

Dated: October 21, 2002

Respectfully submitted,

By _____

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